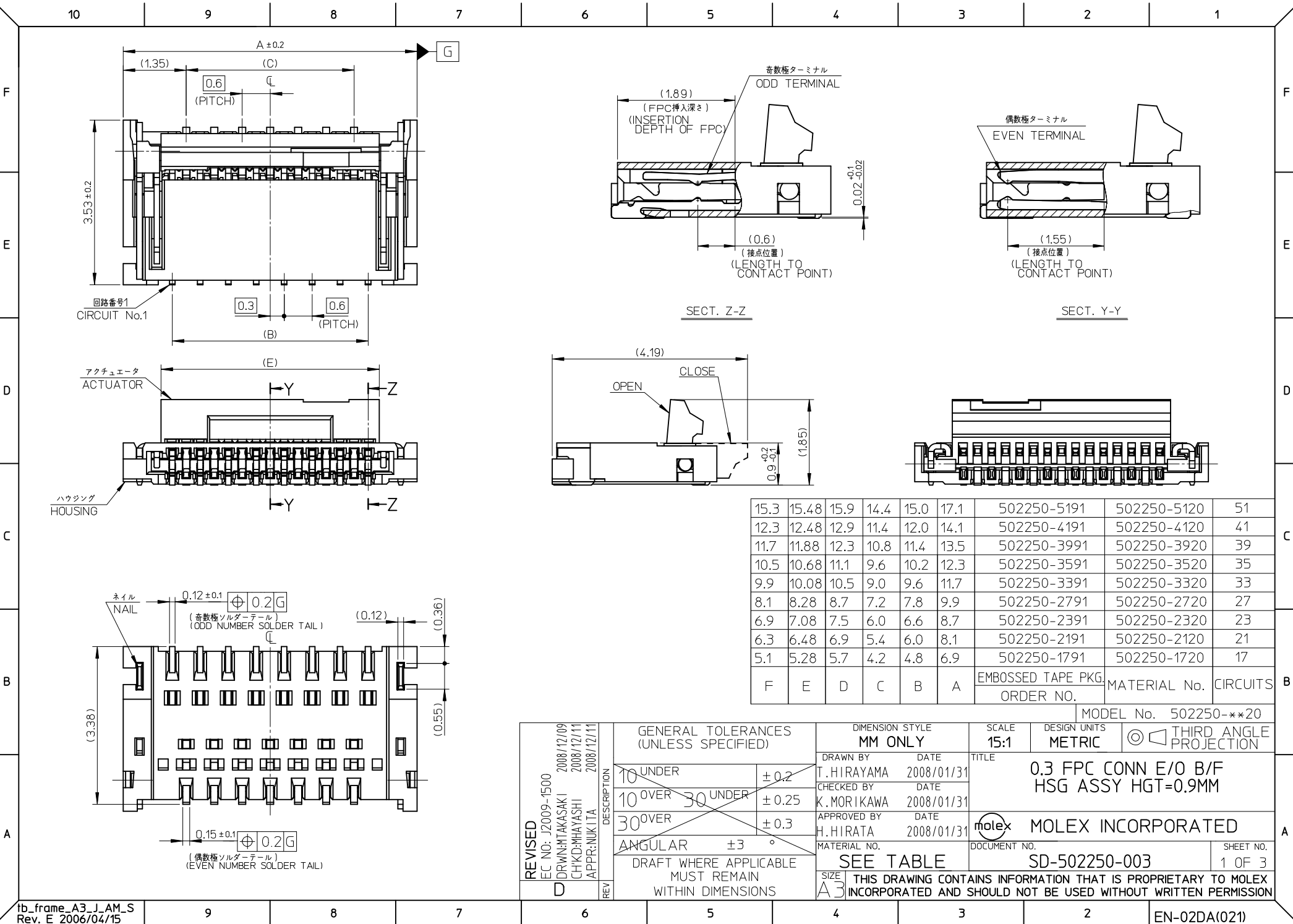




15.3	15.48	15.9	14.4	15.0	17.1	502250-5191	502250-5120	51
12.3	12.48	12.9	11.4	12.0	14.1	502250-4191	502250-4120	41
11.7	11.88	12.3	10.8	11.4	13.5	502250-3991	502250-3920	39
10.5	10.68	11.1	9.6	10.2	12.3	502250-3591	502250-3520	35
9.9	10.08	10.5	9.0	9.6	11.7	502250-3391	502250-3320	33
8.1	8.28	8.7	7.2	7.8	9.9	502250-2791	502250-2720	27
6.9	7.08	7.5	6.0	6.6	8.7	502250-2391	502250-2320	23
6.3	6.48	6.9	5.4	6.0	8.1	502250-2191	502250-2120	21
5.1	5.28	5.7	4.2	4.8	6.9	502250-1791	502250-1720	17
F	E	D	C	B	A	EMBOSSED TAPE PKG ORDER NO.	MATERIAL No.	CIRCUITS

REVISED EC NO: J2009-1500 DRAWN: TAKASAKI CHKD: HAYASHI APPR: NUKITA D	DESCRIPTION 2008/12/09 2008/12/11 2008/12/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		~~10 UNDER~~		~~±0.2~~		DRAWN BY T. HIRAYAMA		DATE 2008/01/31	
		~~10 OVER 30 UNDER~~		~~±0.25~~		CHECKED BY K. MORIKAWA		DATE 2008/01/31	
		~~30 OVER~~		~~±0.3~~		APPROVED BY H. HIRATA		DATE 2008/01/31	
		~~ANGULAR ±3 °~~		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502250-003		1 OF 3	
		REV		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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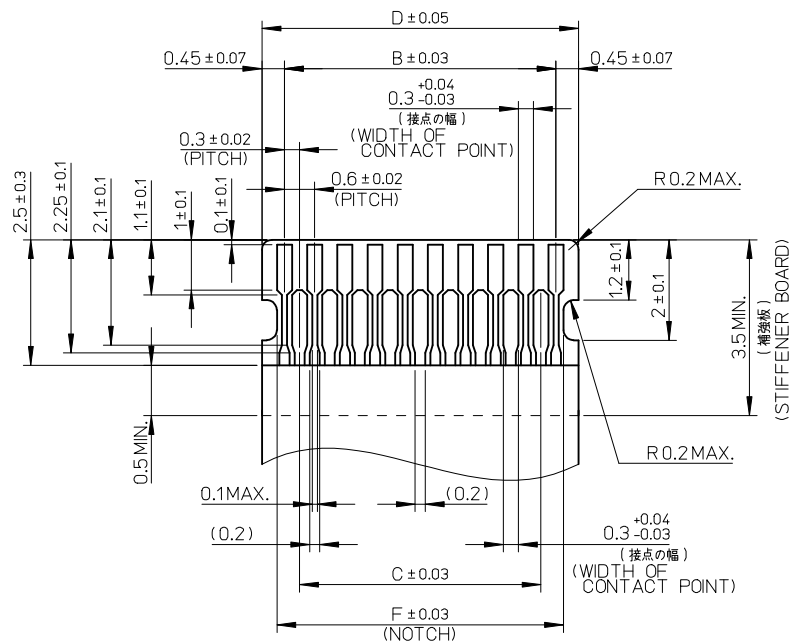
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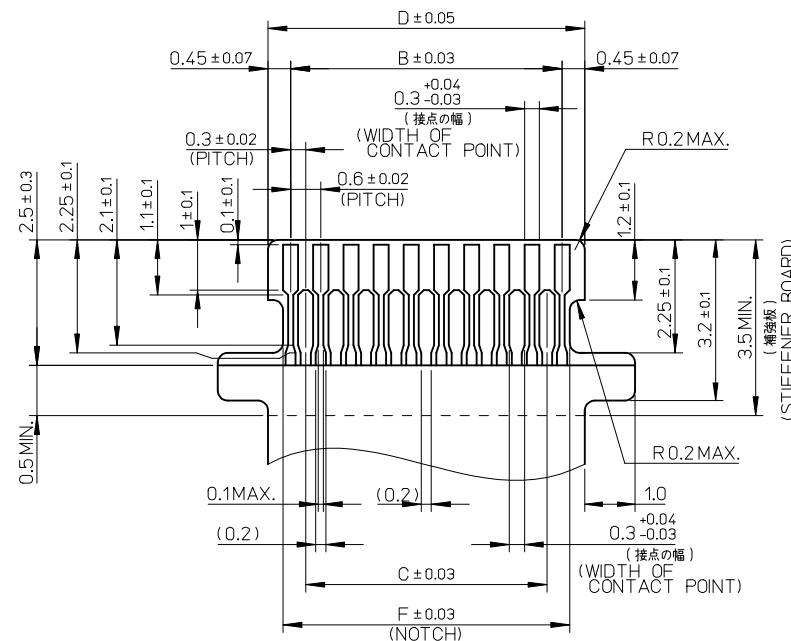
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標準 FPC
STANDARD



挿入位置確認用耳つきFPC
WITH EARS FOR FPC INSERTION ALIGNMENT

嵌合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

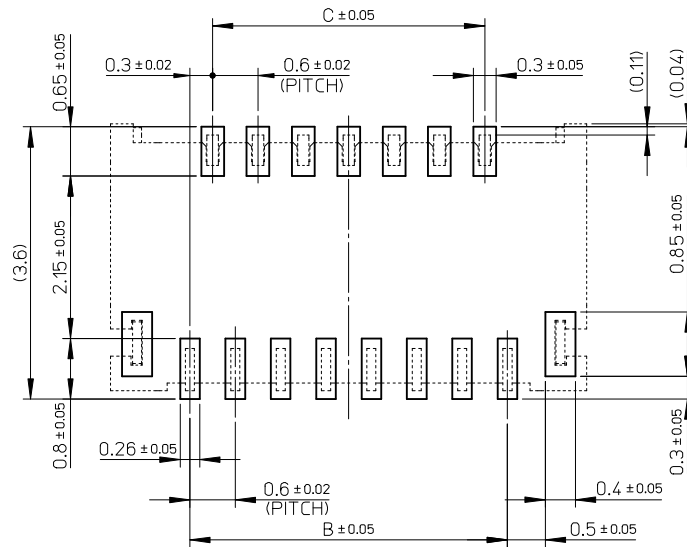
FPCについて:

抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

SEE SHEET 1	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		~~10 UNDER ± 0.2~~		DRAWN BY DATE T.HIRAYAMA 2008/01/31		TITLE 0.3 FPC CONN E/O B/F HSG ASSY HGT=0.9MM				
		~~10 OVER 30 UNDER ± 0.25~~		CHECKED BY DATE K.MORIKAWA 2008/01/31						
		~~30 OVER ± 0.3~~		APPROVED BY DATE H.HIRATA 2008/01/31		MOLEX INCORPORATED				
		~~ANGULAR ± 3 °~~		MATERIAL NO.						DOCUMENT NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-502250-003				2 OF 3
REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



推奨基板レイアウト図 (マウント面)
P.CBOARD PATTERN
RECOMMENDED DIMENSION
(MOUNTING AREA)

注記 NOTES

1. 使用材料 MATERIAL
ハウジング : 液晶ポリマー ガラス充填 UL94V-0 (ナチュラル)
HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0(COLOR:NATURAL)
アクチュエータ : ポリフェニレンサルファイド ガラス充填 UL94V-0 (黒)
ACTUATOR : POLYPHENYLENE SULFIDE (GLASS FILLED)
UL94V-0(COLOR:BLACK)
ターミナル : 銅ニッケルスズ合金、ニッケル下地部分金メッキ (接触部及びテール部)
TERMINAL : COPPER NICKEL TIN ALLOY,
PARTLY GOLD(CONTACT,TAIL) OVER NICKEL PLATING
ネイル : リン青銅、ニッケル下地 錫めっき
FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING
2. ソルダータール半田付け面、及びネイル半田付け面の平坦度 : 0.1mmMAX.
COPLANARITY OF SOLDER TAILS AND FITTING NAILS
TO BE 0.1mm MAX.
3. 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
必ず基板に実装し、FPCを挿入してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON
THE SUBSTRATE,AND MATING FPC.
4. 推奨メタルマスク RECOMMENDED METAL MASK SPECIFICATION
マスク厚 : 0.1mm MASK THICKNESS : 0.1mm
なお、貴社にて上記以外でご利用頂く場合は、事前に確認頂きますようお願い致します。
WHEN USE IT OTHER THAN THE ABOVE IN YOUR COMPANY,
PLEASE CONFIRM IT BEFOREHAND.
5. ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT.

SEE SHEET 1 EC NO.: J2009-1500 DRWN:MTAKASAKI 2008/12/09 CHKD:MHAYASHI 2008/12/11 APPR:NUKITA 2008/12/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY T. HIRAYAMA	DATE 2008/01/31	TITLE 0.3 FPC CONN E/O B/F HSG ASSY HGT=0.9MM				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 2008/01/31					
		30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 2008/01/31	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-502250-003		3 OF 3			
	D	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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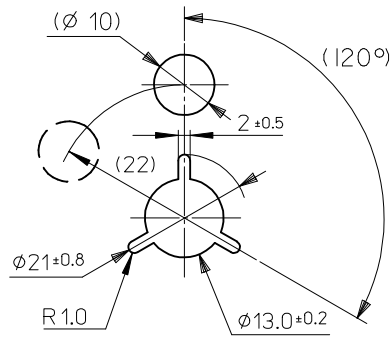
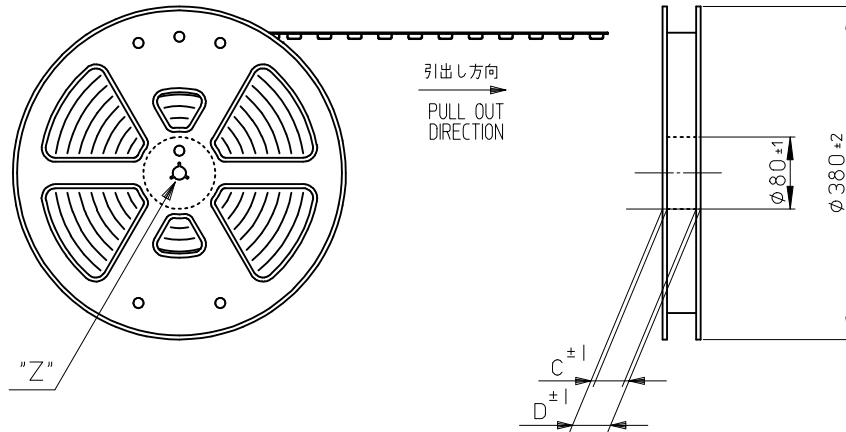
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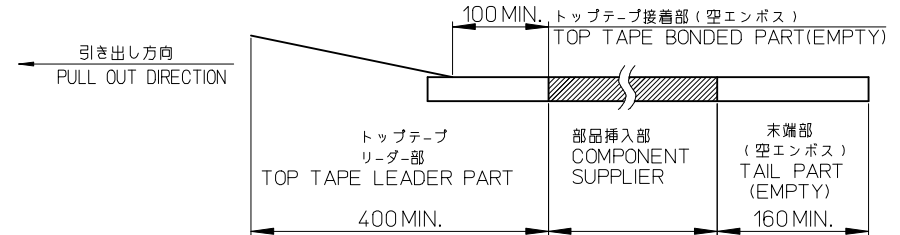
A



DETAIL "Z"

NOTES

- 製品 (502250-**20) の詳細寸法については、
図面SD-502250-003をご参照ください
IN THE PACKAGE, PART NO. 502250-**20 DETAILED DIMENSIONS,
REFER TO SALES DRAWING NO. SD-502250-003.
- 梱包数量: 3000 個/リール
NUMBER OF CONNECTORS:3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE): ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE): PET, OTHER
リール(REEL): ポリスチレン(POLYSTYRENE)<リサイクル材を含む>
<RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT.

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EN-02JA(021)

REVISED EC NO: J2009-1500 DRWN:MTAKASAKI 2008/12/09 CHKD:MHAYASHI 2008/12/11 APPR:NUKITA 2008/12/11 C	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
		10 UNDER	± 0.2	DRAWN BY T. HIRAYAMA DATE 2008/01/31		TITLE 0.3 FPC CONN E/O B/F HGT=0.9MM EMBSTP PKG		
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. MORIKAWA DATE 2008/01/31				
		30 OVER	± 0.3	APPROVED BY H. HIRATA DATE 2008/01/31				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502250-004		1 OF 3	
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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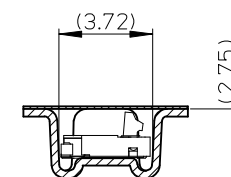
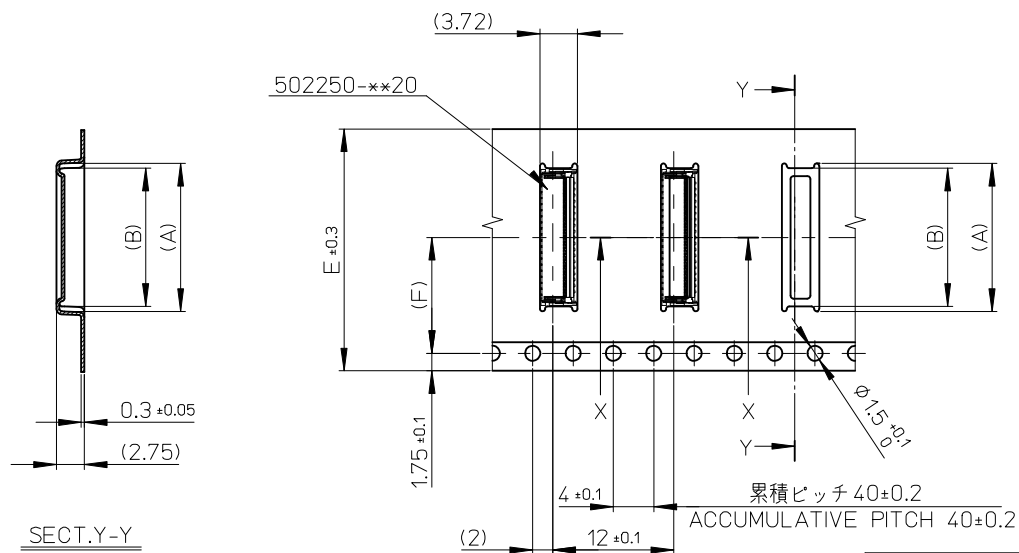
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引き出し方向
PULL OUT DIRECTION



SECT.X-X

SECT.Y-Y

24	11.5	24	29.4	25.4	14.3	15.3	502250-4191	41	
					13.7	14.7	502250-3991	39	
					12.5	13.5	502250-3591	35	
					11.9	12.9	502250-3391	33	
					10.1	11.1	502250-2791	27	
					8.9	9.9	502250-2391	23	
					8.3	9.3	502250-2191	21	
16	7.5	16	21.4	17.4	7.1	8.1	502250-1791	17	
キャリアテープ幅 CARRIER TAPE WIDTH		(F)	E	D	C	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUIT

MODEL No. 502250-**-91

DESIGN UNITS
METRICTHIRD ANGLE
PROJECTION

SEE SHEET 1
EC NO.: J2009-1500
DRWN: MTAKASAKI 2008/12/09
CHKD: HAYASHI 2008/12/11
APPR: NUKITA 2008/12/11

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
T. HIRAYAMA	2008/01/31
CHECKED BY	DATE
K. MORIKAWA	2008/01/31
APPROVED BY	DATE
H. HIRATA	2008/01/31
MATERIAL NO.	

SCALE

TITLE
0.3 FPC CONN E/O B/F
HGT=0.9MM EMBSTP PKG

MOLEX INCORPORATED

SD-502250-004

2 OF 3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

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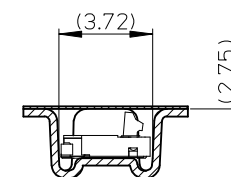
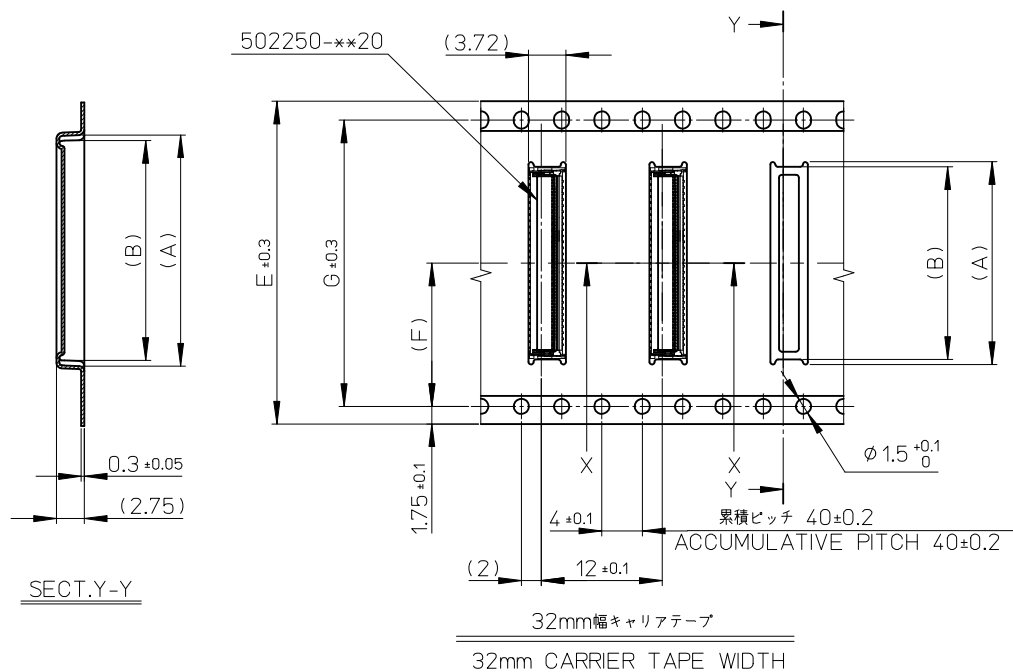
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引き出し方向
PULL OUT DIRECTION



SECT.X-X

32	28.4	14.2	32	37.4	33.4	17.3	18.3	502250-5191	51
キャリアテープ幅 CARRIER TAPE WIDTH	G	(F)	E	D	C	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUIT

SEE SHEET 1 EC NO.: J2009-1500 DRWN: MTAKASAKI 2008/12/09 CHKD: HAYASHI 2008/12/11 APPR: NUKITA 2008/12/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY T. HIRAYAMA	DATE 2008/01/31	TITLE 0.3 FPC CONN E/O B/F HGT=0.9MM EMBSTP PKG			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 2008/01/31				
		30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 2008/01/31				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502250-004		3 OF 3		
	REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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moschip.ru_9